Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type ($L^2-\pi$ -MOSV)

2SK2741

Chopper Regulator, DC-DC Converter and Motor Drive Applications

• 4 V gate drive

 $\begin{array}{ll} \bullet & Low \ drain-source \ ON \ resistance & \vdots \ RDS \ (ON) = 0.12 \ \Omega \ (typ.) \\ \bullet & High \ forward \ transfer \ admittance & \vdots \ |Y_{fs}| = 5.0 \ S \ (typ.) \\ \end{array}$

• Low leakage current : $I_{DSS} = 100 \mu A \text{ (max) (V}_{DS} = 60 \text{ V)}$

• Enhancement-mode : $V_{th} = 0.8 \sim 2.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$

Maximum Ratings (Ta = 25°C)

Characteris	stics	Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	60	V	
Drain-gate voltage (Ro	_{SS} = 20 kΩ)	V_{DGR}	60	٧	
Gate-source voltage		V_{GSS}	±20	V	
Drain current	DC (Note 1)	I _D	5	Α	
	Pulse (Note 1)	I _{DP}	20	A 	
Drain power dissipation	n (Note 2)	P_{D}	2.5	W	
Single pulse avalanche	e energy (Note 3)	E _{AS}	129	mJ	
Avalanche current		I _{AR}	5	Α	
Repetitive avalanche e	nergy (Note 4)	E _{AR}	0.25	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature ra	ange	T _{stg}	-55~150	°C	

DRAIN (HEAT SINK)

2-7H1B

Weight: 0.12 g (typ.)

GATE

SOURCE

Marking

JEDEC
JEITA
TOSHIBA

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient	R _{th (ch-a)}	50	°C/W



Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: Mounted on ceramic substrate (25.4 mm × 25.4 mm × 0.8 mm)

Note 3: V_{DD} = 25 V, T_{ch} = 25°C (initial), L = 7 mH, R_G = 25 Ω , I_{AR} = 5 A

Note 4: Repetitive rating; Pulse width limited by maximum channel temperature.

This transistor is an electrostatic sensitive device.

Please handle with caution.



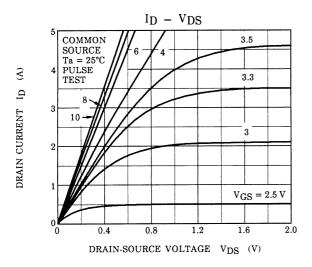
Electrical Characteristics (Ta = 25°C)

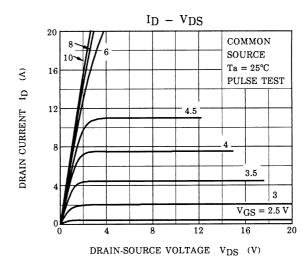
Charac	eteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I _{GSS}	V _{GS} = ±16 V, V _{DS} = 0 V		_	±10	μΑ
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 60 V, V _{GS} = 0 V		_	100	μA
Drain-source br	eakdown voltage	V _{(BR)DSS}	I _D = 10 mA, V _{GS} = 0 V	60	_	_	V
Gate threshold v	oltage/	V_{th}	V _{DS} = 10 V, I _D = 1 mA	0.8	_	2.0	V
Drain-source ON resistance		R _{DS (ON)}	V _{GS} = 4 V, I _D = 1.3 A	_	0.20	0.30	Ω
			V _{GS} = 10 V, I _D = 2.5 A	_	0.12	0.16	
Forward transfer	r admittance	Y _{fs}	V _{DS} = 10 V, I _D = 2.5 A	3.0	5.0	_	S
Input capacitano	e	C _{iss}		_	370	_	
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	60	_	pF
Output capacitance		Coss		_	180	_	
Switching time	Rise time	t _r	V_{GS}_{0V} $I_{D}=2.5A$ $R_{L}=12\Omega$ $V_{DD}=30V$	_	18	_	ns
	Turn-on time	t _{on}		_	25	_	
	Fall time	t _f		_	55	_	
	Turn-off time	t _{off}	Duty $\leq 1\%$, $t_{W} = 10 \mu s$	_	170	_	
Total gate charge (gate-source plus gate-drain)		Qg		_	12	_	
Gate-source charge		Q _{gs}	$V_{DD} \approx 48 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 5 \text{ A}$		8	_	nC _
Gate-drain ("miller") Charge		Q _{gd}			4	_	

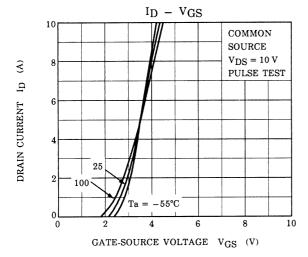
Source-Drain Ratings and Characteristics (Ta = 25°C)

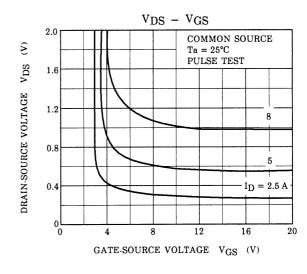
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	5	Α
Pulse drain reverse current (Note 1)	I _{DRP}	-	_	_	20	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 5 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 5 A, V _{GS} = 0 V, dI _{DR} / dt = 50 A / µs	_	70	_	ns
Reverse recovery charge	Q _{rr}	1DR = 3 A, VGS = 0 V, αιDR / αι = 50 A / μs		0.1	_	μC

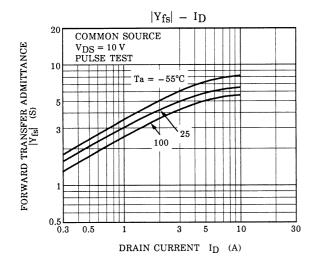
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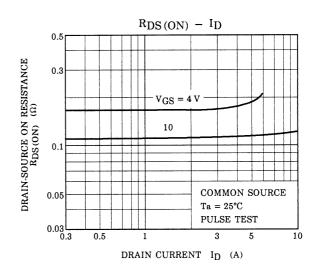




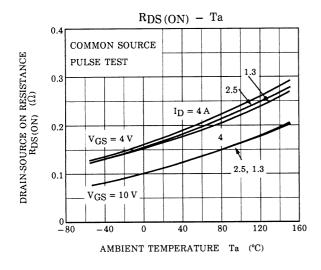


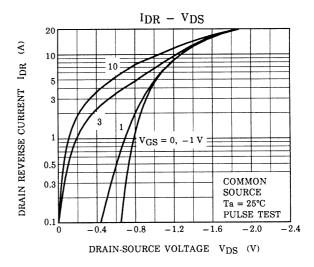


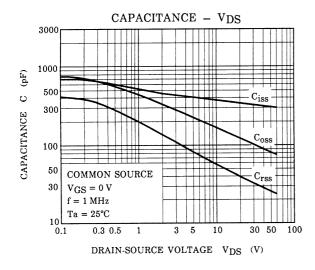


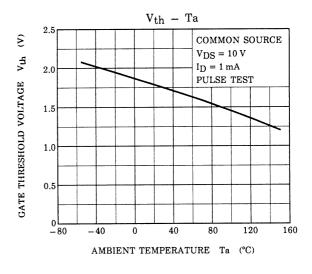


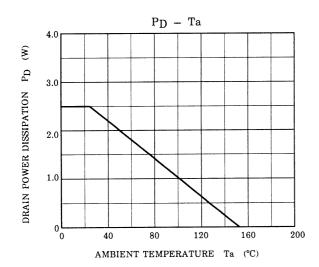
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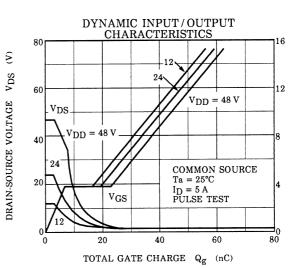




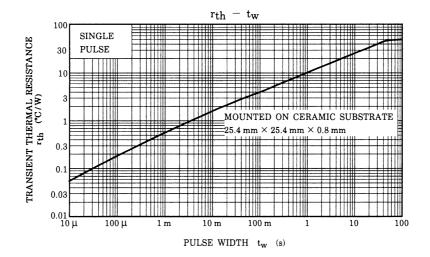


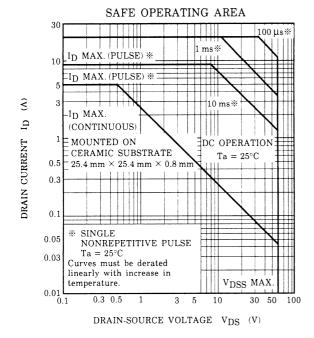


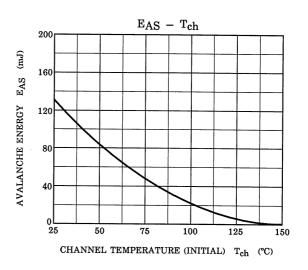


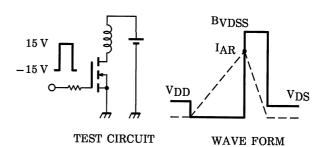


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$$R_G$$
 = 25 Ω
 V_{DD} = 25 V, L = 7 mH

$$EAS = \frac{1}{2} \cdot L \cdot I^{2} \cdot \left(\frac{BVDSS}{BVDSS - VDD} \right)$$

RESTRICTIONS ON PRODUCT USE

000707EAA

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